

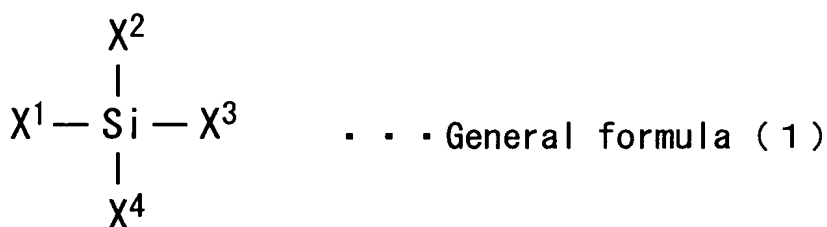
Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. - 19. (Canceled)

20. (Currently Amended) An adhesive comprising a resin component, a metal chelate, and a silane coupling agent,

wherein said resin component includes a thermosetting resin and said silane coupling agent is composed of a silane compound represented by general formula (1):



wherein at least one of substituents X¹ through X⁴ is an alkoxy group, and wherein if one or more of the substituents X¹ through X⁴ is a substituent other than alkoxy group, such substituent other than alkoxy group is a substituent that includes in its structure a functional group selected from the group consisting of epoxy ring, vinyl group, amino group, mercapto group and methyl group,

wherein the metal chelate is microcapsulated,

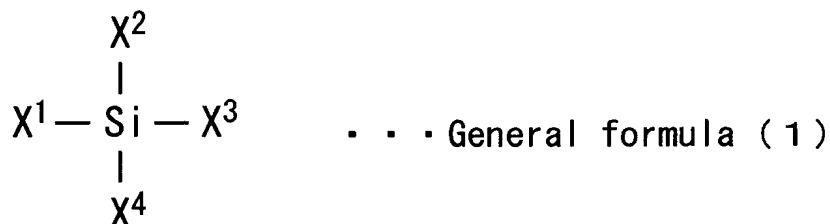
wherein the adhesive is in the form of a paste,

~~The adhesive according to claim 1,~~ wherein microcapsules are formed as absorbent resin particles and dispersed in the adhesive, and

wherein the metal chelate is liquid, and the metal chelate is absorbed by and retained in the microcapsules.

21. - 22. (Canceled)

23. (Currently Amended) An adhesive film obtained by forming an adhesive composition into a film,
the adhesive composition comprising a resin component, a metal chelate, and a silane coupling agent,
wherein said resin component includes a thermosetting resin, and said silane coupling agent is composed of a silane compound represented by general formula (1):



wherein at least one of substituents X¹ through X⁴ is an alkoxy group, and wherein if one or more of the substituents X¹ through X⁴ is a substituent other than alkoxy group, such substituent other than alkoxy group is a substituent that includes in its structure a functional group selected from the group consisting of epoxy ring, vinyl group, amino group, mercapto group and methyl group, and

wherein the metal chelate is microcapsulated so as to be a microcapsule, and the microcapsule is dispersed in the adhesive film,

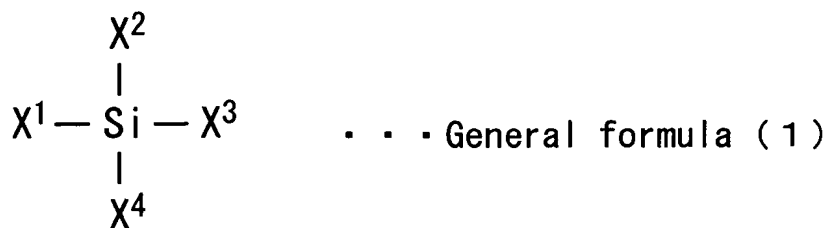
~~The adhesive film according to claim 15,~~ wherein microcapsules are formed as absorbent particles and dispersed in the adhesive film, and

wherein the metal chelate is liquid, and the metal chelate is absorbed by and retained in the microcapsules.

24. - 25. (Canceled)

26. (Previously Presented) An adhesive comprising a resin component, a metal chelate, and a silane coupling agent,

wherein said resin component comprises a thermosetting resin and said silane coupling agent comprises a silane compound represented by general formula (1):



wherein at least one of substituents X^1 through X^4 is an alkoxy group, and wherein if one or more of the substituents X^1 through X^4 is a substituent other than alkoxy group, such substituent other than alkoxy group is a substituent that includes in its structure a functional group selected from a group consisting of epoxy ring, vinyl group, amino group, mercapto group and methyl group, and

wherein the silane coupling agent is microcapsulated.

27. (New) The adhesive according to claim 26, wherein said alkoxy group is a methoxy group.

28. (New) The adhesive according to claim 26, wherein said alkoxy group is an ethoxy group.

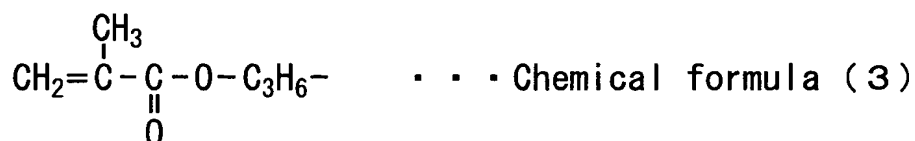
29. (New) The adhesive according to claim 26, wherein at least one of the substituents X^1 through X^4 of said silane compound is a substituent other than alkoxy and at least one of said substituents other than alkoxy has an epoxy ring.

30. (New) The adhesive according to claim 26, wherein at least one of the substituents X^1 through X^4 of said silane compound is a substituent other than alkoxy and at least one of said substituents other than alkoxy has a vinyl group.

31. (New) The adhesive according to claim 29, wherein said substituent having the epoxy ring is a γ -glycidoxypropyl group represented by chemical formula (2):



32. (New) The adhesive according to claim 30, wherein said substituent having the vinyl group is a γ -methacryloxypropyl group represented by chemical formula (3):



33. (New) The adhesive according to claim 26, wherein an amount of said metal chelate is from 0.1 parts by weight to 20 parts by weight with respect to 100 parts by weight of said resin component and an amount of said silane coupling agent is from 0.1 parts by weight to 35 parts by weight with respect to 100 parts by weight of said resin component.

34. (New) The adhesive according to claim 26, wherein said resin component includes a thermoplastic resin and an amount of said thermoplastic resin is 10 parts by weight or more with respect to 100 parts by weight of said thermosetting resin.

35. (New) The adhesive according to claim 33, wherein said resin component includes a thermoplastic resin and an amount of said thermoplastic resin is 10 parts by weight or more with respect to 100 parts by weight of said thermosetting resin.

36. (New) The adhesive according to claim 26, wherein said thermosetting resin is an epoxy resin.

37. (New) The adhesive according to claim 36, wherein the epoxy resin is an alicyclic epoxy resin.

38. (New) The adhesive according to claim 26, wherein said metal chelate includes an aluminum chelate as a major constituent.

39. (New) The adhesive according to claim 33, wherein said metal chelate includes an aluminum chelate as a major constituent.

40. (New) The adhesive according to claim 26, wherein the metal chelate is a powder or liquid.